

Abstract

RESIN COMPOSITION, AND PREPREG AS WELL AS LAMINATE USING
THE SAME

[Problem to be solved]

To provide a resin composition which can be suitably used in a printed wiring board having high glass transition temperature, high copper foil peel strength, heat resistance in moisture absorption, flame resistance, resistance to soldering heat, low water absorption and high heat dissipation characteristics, and a prepreg using the resin composition, and a laminate as well as a metal foil-clad laminate using the prepreg.

[Solution]

There is used a resin composition comprising an epoxy resin (A), a curing agent (B), a first filler (C), a second filler (D) and a wetting dispersant (E), wherein the first filler (C) is borate particles coated with hexagonal boron nitride.